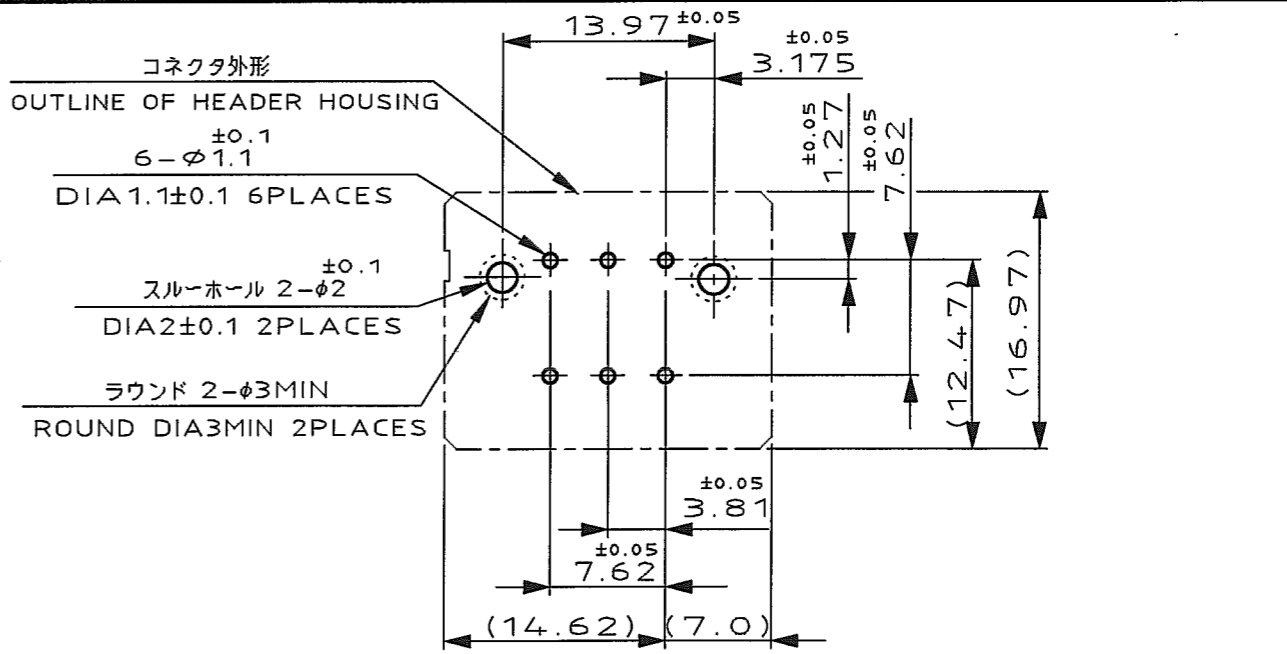
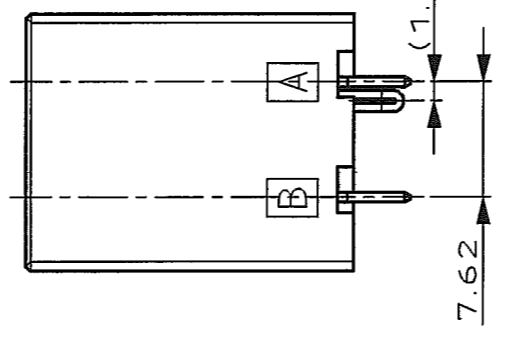
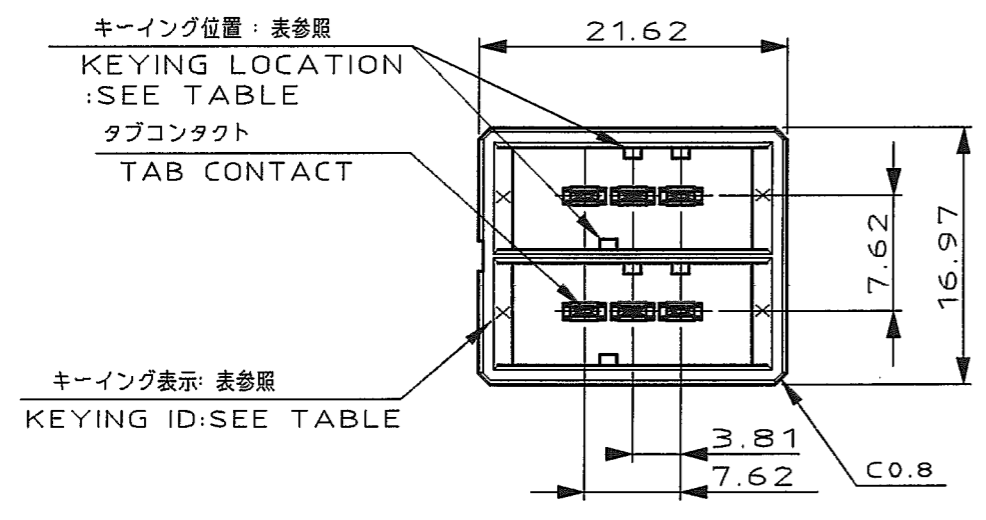
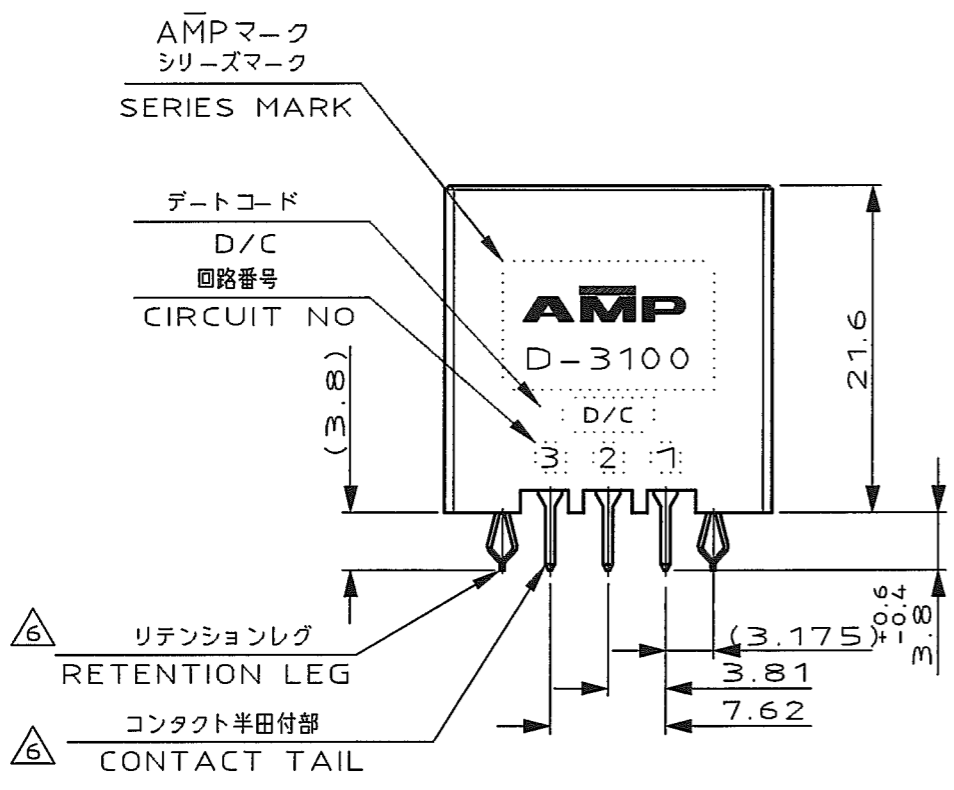


NUMBER 178141  
 METRIC  
 DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT  
 PRINT DIST  
 AMP-J REV.10/83



推奨基板取付け穴寸法  
 PC 基板厚: 1.6  $\pm 0.1$   
 (非累積公差)  
 (コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN  
 PC BOARD THICKNESS: 1.6  $\pm 0.1$   
 (NOT ACCUMULATE TOLERANCE)  
 (CONNECTOR MOUNT SIDE)



NOTES

- MATERIAL: HOUSING: GLASS FILLED THERMO PLASTIC, POLYESTER (94V-0), COLOR: BLACK  
 CONTACT: COPPER ALLOY  
 RETENTION LEG: COPPER ALLOY
- FINISH (CONTACT AREA): 0.38  $\mu$ m MIN GOLD PLATING OVER NI PLATING
- FINISH (CONTACT AREA): 0.76  $\mu$ m MIN GOLD PLATING OVER NI PLATING
- FINISH (CONTACT AREA): 2.0  $\mu$ m MIN TIN PLATED OVER NICKEL
- FINISH (RETENTION LEG): TIN-LEAD PLATED (CONTACT TAIL) OVER NICKEL
- FINISH (RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL

注記

- 材料: ハウジング: ガラス入り熱可塑性ポリエステル樹脂 (94V-0), 色: 黒  
 コンタクト: 銅合金  
 リテンションレグ: 銅合金
- めっき: コンタクト: 全面Ni下地  
 接触部: 0.38  $\mu$ m MIN金めっき
- めっき: コンタクト: 全面Ni下地  
 接触部: 0.76  $\mu$ m MIN金めっき
- めっき: コンタクト: 全面Ni下地  
 接触部: 2.0  $\mu$ m MINスズめっき
- めっき: リテンションレグとコンタクト半田付部  
 ニッケル下地の上に半田めっき
- めっき: リテンションレグとコンタクト半田付部  
 ニッケル下地の上にスズめっき

A ROW		X	Y	△6	△4	3-178141-5
B ROW				△6	△3	3-178141-3
A ROW		X	X	△6	△4	1-178141-5
B ROW				△6	△3	1-178141-3
				△6	△2	1-178141-2
KEYING LOCATION				A ROW KEYING	B ROW KEYING	製品番号 PART NO.

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E	REVISED	FJD0-0039-03	TS	S.M.	6/2/83	WIRE RANGE	
D	REVISED	FJD0-0114-03	TS	S.M.	25 APR '03	INSULATION DIA	
C	REVISED	FJ00-1686-94	KI	S.M.	12/20 '94	NAME	
B	REVISED	FJ00-0838-94	NM	S.M.	7/4 '94	DYNAMIC D-3100 3.81X7.62PITCH(V) 6 POS.HDR CONN.ASS'Y	
A	REDRAWN WITH CHANGE	FJ00-0480-94	NM	S.M.	4/20 '94	一般公差 (GENERAL TOLERANCE)	
LTR	REVISION RECORD	DR	CHK	DATE	CHK.	APP.	SCALE
					N. Matsubara	N. Matsubara	A3 J
					S. MANABE	S. MANABE	REV. E
							SHEET 1 OF 1